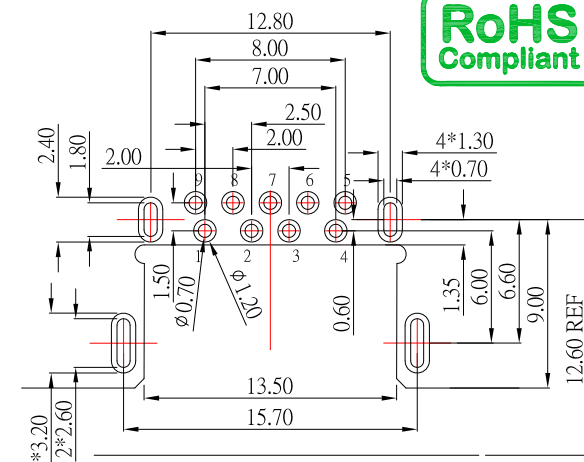
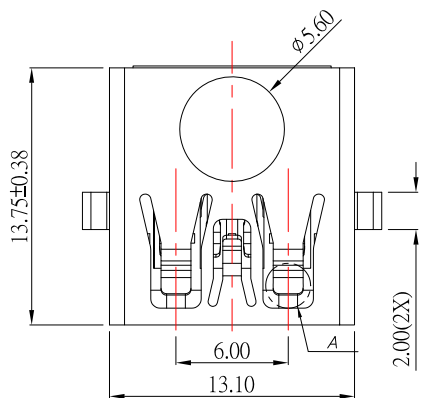




# SUA-110E18-30x-S242

鍍層厚度：

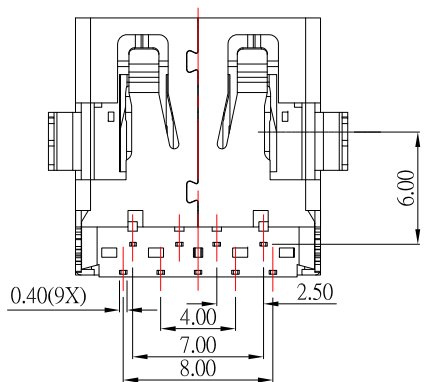
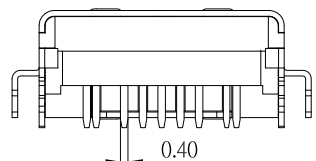
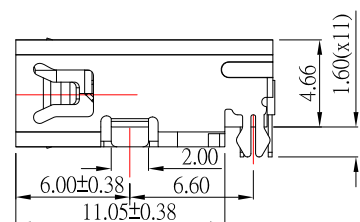
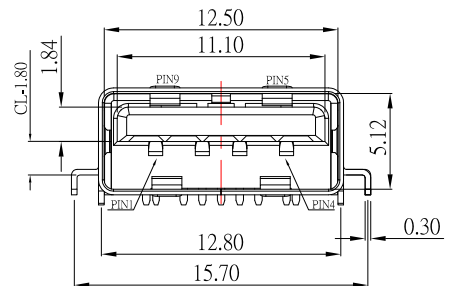
Blank	: 1u"
2	: 15u"
3	: 30u"



## RECOMMENDED PCB LAYOUT

NOTE:

- 1.MATERIAL:
  - 1.1 Housing: LCP
  - 1.2 Contact: Phosphor Bronze
  - 1.3 Shell: SUS201
- 2.Finish:
  - 2.1 Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
  - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
  - 3.1 Rate: 30V DC , 1.5 A
  - 3.2 Insulator Resistance:100MΩ Min
  - 3.3 Dielectric Strength: 500V AC
  - 3.4 Contact Resistance: 30mΩ Max
  - 3.5 Operation Temperature: -55°C ~ +85°C



**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu  
CHECKED BY: Jacky Chen  
APPROVED BY: Tony Kao

DATE: 03/29/22  
DATE: 03/29/22  
DATE: 03/29/22

MAT'L  
FINISH  
SCALE: 1 : 1  
SHEET NO. 1 of 1

TITLE: CONNECTOR  
MODLE: USB AF 3.0 SMT 沉板板上H4.46mm L13.75 無捲邊  
DWG NO. SUA-110E18-30x-S242  
PART NO. SUA-110E18-30x-S242

SIZE: A4  
VER: R2

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	新增尺寸和更新樣式	Jack	032922
1	更新樣式	Jack	032522